

S/N 09/253,611

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Ron Pompey

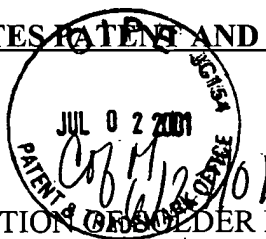
Serial No.: 09/253,611

Group Art Unit: 2812

Filed: February 19, 1999

Docket: 303.572US1

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS



11/C
7/12/01
Harrison

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on March 28, 2001. Please amend the above-identified patent application as follows.

IN THE DRAWINGS

Enclosed is a copy of Figure 6 of the drawings showing the following proposed amendment to Figure 6 in red ink. Reference numerals 210 and 215 are added to Figure 6. Support for these amendments to the drawings can be found on page 11, lines 24-28 of Applicant's disclosure and Figure 5, thus no new matter is introduced.

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IN THE CLAIMS

Please add new claims 68- 75 as follows:

68.(New) The method recited in claim 1 performed in the order recited.

69.(New) The method recited in claim 13 performed in the order recited.

70.(New) The method recited in claim 13 wherein electrolytically depositing solder on the exposed portion of the metal contact pad, includes forming a solder contact extending below the resist layer and below a surface of the insulating layer;

07/06/2001 CCHAU1 00000130 190743 09253611

01 FC:103 144.00 CH
02 FC:102 400.00 CH

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